

# Bill of Materials

TI DESIGNS



Item	Part Name	Mfr P/N	Package	Title Detail	Mfr Name	Priority Level	Reference	Qty
1	PCB	XLB430BOOST-C55AUDIO1_V2.0		FR-4,4-LAYERS,RED	Huatao	1		1
2	IC	MSP430G2553IN20	PDIP20	no-pop.put in to ESD bag	TI	1		0
3	IC	TPS61041DBVR	SOT-23-5		TI	1	U12	1
4	IC	SN74AVC4T245PWT	TSSOP16		TI	1	U11	1
5	IC	TPS79533DCQR	SOT223		TI	1	U9	1
6	IC	TPS77801D	SOIC8		TI	1	U1	1
7	IC	TLV320AIC32041RHBT	QFN32		TI	1	U2	1
8	IC	TPS62260DDCT	SOT563		TI	1	U6	1
9	IC	TMX320C5535SZHH	BGA144		TI	1	U5	1
10	IC	INA219AIDCNR	SOT23		TI	1	U3	1
11	IC	TS3A225ERTER	QFN16		TI	1	U7	1
12	IC	TPS79501DCQ	SOT-223-6		TI	1	U8	1
13	IC	APM2301CAC-TRG	SOT-23		SINO	1	Q1	1
14	OSC	DSCA12.0000NNS	3225	OSC,SMT,12 MHZ,3.3V CRYSTAL 32.768KHZ 12.5PF 20PPM	Hosonic	1	U4	1
15	CRYSTAL	DST410S	4115		KDS	1	Y1	1
16	Diode	19-213-G6C-BM1N2B-3T(LED0603GF)	0603		EVERLIGHT	1	D3	1
17	Diode	DL5234B	LL34		HY	1	D2	1
18	Diode	25-21/T1D-ANQHY/2A	1206		EVERLIGHT	1	D14	1
19	Diode	24-21SURC/S530-A2/TR8	SOP		EVERLIGHT	1	D6-D13	8
20	Diode	MBR0520LT1G	SOD-123		Onsemi	1	D1.D4.D5	3
21	OLED	UG-9616TLBBG01	SOP		Univision	1		1
22	Bead	CBG201209U151T (0805-150R±25%)	0805		Fenghua	1	L1.L2	2
23	Inductance	BLM18AG601SN1D(0603-600R±25%)	0603		MURATA	1	L3.L4.L5.L6.L7.L8	6
24	Inductance	VL3010AT-2R2M1R0	SMD		TDK	1	L9.L11	2
25	Cap.	CC0402JRNPO9BN330(C0402-33PJ/50V)	0402		YAGEO	1	C23.C24.C79	3
26	Cap.	CC0402KRX7R9BB222(C0402-222K/50V)	0402		YAGEO	1	C72.C220	2
27	Cap.	CA100UF/10VC(TAJC107K010RNJ)	C size		AVX	1	C13.C15	2
28	Cap.	CC0402JRNPO9BN100(C0402-10PJ/50V)	0402		YAGEO	1	C103	1
29	Cap.	CC0402KRX7R9BB102(C0402-102K/50V)	0402		YAGEO	1	C20.C31.C45.C58	4
30	Cap.	CC0402KRX7R9BB103(C0402-103K/50V)	0402		YAGEO	1	C28.C36.C38.C42.C51.C 53.C55.C83	8
31	Cap.	CC0402KRX7R9BB104(C0402-104K/50V)	0402		YAGEO	1	C4.C5.C8.C9.C14.C17.C 19.C22.C25.C27.C30.C3 2.C33.C34.C41.C44.C46. C47.C48.C49.C50.C57.C 59.C60.C61.C63.C64.C6 5.C66.C67.C68.C70.C71. C75.C80.C88.C108.C200 .C201.C202.C210	41
32	Cap.	CL05A104KA5NNNC (0402-104K/25V)	0402		SAMSUNG	1	C4.C5.C8.C9.C14.C17.C 19.C22.C25.C27.C30.C3 2.C33.C34.C41.C44.C46. C47.C48.C49.C50.C57.C 59.C60.C61.C63.C64.C6 5.C66.C67.C68.C70.C71. C75.C80.C88.C108.C200 .C201.C202.C210	41
33	Cap.	CC0402KRX5R6BB474(C0402-474K/10V)	0402		YAGEO	1	C10.C12.C111	3
34	Cap.	CL05A474KP5NNNC/C0402-474K/10V	0402		SAMSUNG	2	C10.C12.C111	3
35	Cap.	CC0603KRX7R7BB105(C0603-105K/16V)	0603		YAGEO	1	C26.C35.C37.C39.C40.C 43.C52.C54.C69.C81.C8 2.C87.C89.C104.C109.C 110.C203.C208.C209.C2 11	20
36	Cap.	CL10B105KO8NNNC(C0603-105K/16V)	0603		SAMSUNG	1	C26.C35.C37.C39.C40.C 43.C52.C54.C69.C81.C8 2.C87.C89.C104.C109.C 110.C203.C208.C209.C2 11	20
37	Cap.	CC0603KRX5R9BB225(C0603-225K/50V)	0603		YAGEO	1	C100.C101	2
38	Cap.	CL10A225KO8NNNC(C0603-225K/16V)	0603		SAMSUNG	2	C100.C101	2
39	Cap.	CC0805KRX7R9BB475(C0805-475K/50V)	0805		YAGEO	1	C73.C76.C77.C78.C85	5
40	Cap.	CL21A475KAQNETE(C0805-475K/25V)	0805		SAMSUNG	2	C73.C76.C77.C78.C85	5
41	Cap.	CC0805KRX5R7BB106(C0805-106K/16V)	0805		YAGEO	1	C1.C2.C6.C7.C16.C18.C 21.C29.C56.C62.C74.C1 02.C105.C206	14
42	Cap.	CL21A106KOQNNNE(C0805-106K/16V)	0805		SAMSUNG	2	C1.C2.C6.C7.C16.C18.C 21.C29.C56.C62.C74.C1 02.C105.C206	14
43	Res.	RC0402JR-070RL	0402		YAGEO	1	R3.R4.R7.R11.R21.R26. R28.R31.R44.R45.R46.R 48.R57.R58.R59.R79.R8 9	17
44	Res.	RC0402JR-07300RL	0402		YAGEO	1	R19.R23	2
45	Res.	RC0402JR-07220RL	0402		YAGEO	1	R40	1
46	Res.	RC0402JR-07330RL	0402		YAGEO	1	R15.R17.R18.R78.R83.R 84.R85.R86.R87	9
47	Res.	RC0402JR-07100KL	0402		YAGEO	1	R25.R36.R37.R91	4
48	Res.	RC0402JR-071KL	0402		YAGEO	1	R14	1
49	Res.	RC0402JR-072K2L	0402		YAGEO	1	R12	1
50	Res.	RC0402JR-074K7L	0402		YAGEO	1	R6.R16.R22.R56	4
51	Res.	RC0402JR-07220KL	0402		YAGEO	1	R92	1
52	Res.	RC0402FR-0710KL	0402		YAGEO	1	R5.R13.R27.R30.R33.R3 4.R35.R38.R39.R41.R47. R64.R67.R68.R70.R71.R	20
53	Res.	RC0402FR-0747KL	0402		YAGEO	1	R9.R10	2
54	Res.	RF0402-3.3K	0402		Uniohm	2	R50	1
55	Res.	RC0402FR-0714KL	0402		YAGEO	1	R20	1
56	Res.	RF0402-14K	0402		Uniohm	2	R20	1
57	Res.	RF0402-30K	0402		Uniohm	2	R54	1

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58	Res.	RF0402-180K	0402		Uniohm	2	R81	1
59	Res.	RC0402FR-07240KL	0402		YAGEO	1	R53	1
60	Res.	RF0402-240K	0402		Uniohm	2	R53	1
61	Res.	RC0402FR-0718K2L	0402		YAGEO	1	R49	1
62	Res.	RF0402-18.2K	0402		Uniohm	2	R49	1
63	Res.	RC0402FR-0710K7L	0402		YAGEO	1	R51	1
64	Res.	RF0402-10.7K	0402		Uniohm	2	R51	1
65	Res.	RF0402-39.2K	0402		Uniohm	2	R95	1
66	Res.	RC0402FR-07110KL	0402		YAGEO	1	R52	1
67	Res.	RF0402-110K	0402		Uniohm	2	R52	1
68	Res.	RC0402FR-07392KL	0402		YAGEO	1	R77	1
69	Res.	RF0402-392K	0402		Uniohm	2	R77	1
70	Res.	RC0402FR-071M6L	0402		YAGEO	1	R80	1
71	Res.	RF0402-1.6M	0402		Uniohm	2	R80	1
72	Res.	RC0402FR-071RL	0402		YAGEO	1	R90	1
73	Res.	RF0402-1R	0402		Uniohm	2	R90	1
74	Res.	RC0402FR-0720KL	0402		YAGEO	1	R94	1
75	Res.	RF0402-20K	0402		Uniohm	2	R94	1
76	Res.	RC0402FR-073K3L	0402		YAGEO	1	R50	1
77	Res.	RC0402FR-0730KL	0402		YAGEO	1	R54	1
78	Res.	RC0402FR-07180KL	0402		YAGEO	1	R81	1
79	Res.	RC0402FR-0739K2L	0402		YAGEO	1	R95	1
80	Connector	R-211-0211-0021-001/1*2-2.54	DIP	CONN 1*2PIN MALE HEADER,2.54MM,VERTICAL	NEXTRON	1	JP3,JP6	2
81	Connector	CNT-MINIUSB-5P	SOP	CONN,SMT,RECETACLE,MI NIUSB,5 POS,RIGHT ANGLE	CNT	1	USB1	1
82	Connector	KJ-355-X1	SMT	CONN,SMT,STEREO JACK,3.5MM	Kalor	1	U13	1
83	Connector	CNT-F254-1*10-GM2-710-L	SMT	CONN 1*10PIN,2.54MM,female header,SMD	CNT	1	P3,P4	2
84	Connector	WQ20832-M001-7F	SMT	SMT,RECEPTACLE,MICROS D, REVERSE	FOXCONN	1	J1	1
85	Connector	STF-08AB05	SMT	SMT,RECEPTACLE,MICROS D, REVERSE	Smartconn	2	J1	1
86	Connector	CNT-FPC0.5-14-TDM/FPC-14P-0.5	SMT	CONN FPC 14POS .5MM R/A SMD GOLD	CNT	1	J2	1
87	PC board			PC material, color silk- screen,sitck on captouch top	Datang	1		0
88	MICRO SD CARD	OO-SDSDQ-2048		MicroSD card, 2GB	Sandisk	1		1
89	Screw			M2*5mm	Hengjia	1		2
90	Copper Pillar			M3.3*14mm copper pillar, through hole, outside diameter		1		
91	Double Sided Coating			3.3mm, inside diameter2mm	Hengjia	1		2
92	JUMPER	2228BG		EVA,22*7*1mm	Datang	1		1
93	USB CABLE			2.54MM	NEXTRON	1		2
94	CNT-YX-IP520			A TO MINI B,600MM,BALCK	CNT	1		1
95	Legal Agreement			3.5MM headset with mic,iphone standerd	CNT	1		0
96	Quick Start Guide			Size:210*280mm, black printing,single side	Datang	1		0
97	Lable			Size:210*285mm,color printing,double side	Datang	1		0
98	Paper box			Sticked on the side of paper box, size: 30*20mm	Lixiang	1		0
99	Cut board				Fuqing	1		0
100	ESD Bag			130*100mm, inner size, trilateral seal, leaving the mouth	Qunlihui	1		0
101	ESD Bag			65*40mm, inner size, trilateral seal, leaving the mouth	Qunlihui	1		0
102	ESD Sponge			140*105*8mm,black	Qunlihui	1		0

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